

| | Type | L # | Hits | Search Text | DBs | Time Stamp | Comments |
|---|------|------|-------|--|---|------------------|----------|
| 5 | BRS | L622 | 16634 | (Ta or tantatalum or TaN or Ta?TaN or TaN?Ta) and (pad or bondpad) | USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM TDB | 2004/10/19 20:45 | |
| 7 | BRS | L624 | 7850 | 622 and (Cu or copper or seed\$6) | USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM TDB | 2004/10/19 20:46 | |
| 8 | BRS | L625 | 2116 | 622 and (Ni or nickel) and (Au or gold) | USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM TDB | 2004/10/19 20:47 | |
| 9 | BRS | L626 | 1803 | 625 and 624 | USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM TDB | 2004/10/19 20:47 | |

| | Type | L # | Hits | Search Text | DBs | Time Stamp | Comments |
|----|------|------|------|--|--|----------------------|----------|
| 10 | BRS | L627 | 1383 | 626 and (semiconductor or chip or die or IC or (integrated adj circuit)) | USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM_ TDB | 2004/10/1 9 20:47 | |
| 11 | BRS | L628 | 974 | 627 and (passivat\$6 or dielectric or isolation or inuslat\$6) | USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM_ TDB | 2004/10/1 9 20:48 | |